AMENDMENTS TO THE SPECIFICATION

Please amend the paragraph beginning on page 11, line 23 and ending on page 12, line 7, as follows:

Even though the melted solder diffuses on the surface of the gold plating area 4 of the terminal portion 2, the diffusion of the melted solder stops at the boundary between the diffusion preventing area ~~4 (SIC)~~ 6 and the gold plating area 4 due to low wetting property between the surface of the diffusion preventing area 6 and the solder. Consequently, it is possible to prevent not only the diffusion of the melted solder to the contacting portion 3, but also the reduction of the quantity of the solder remained at the terminal portion 2. Furthermore, the connecting strength of the terminal portion 2 on the printed circuit board 110 can be maintained higher.

Please amend the paragraph on page 15 beginning at line 9 and ending at line 14, as follows:

Furthermore, the direction for irradiating the laser beams L is slanted by a predetermined angle θ with respect to a plate portion of the semi-finished blank 12 so as not to occur any portion where the laser beams L are not irradiated due to hidden by another portion of the contact 1 such as a flexion ~~20 (SIC)~~ 30 corresponding to the shape of the contact 1, as shown in FIG. 8.

Please amend the paragraph on page 20 beginning at line 24 and ending on page 21 at line 12, as follows:

In the method for forming the diffusion preventing area in the third embodiment, the flexion 19 between the terminal portion 2 and the contacting portion 3 of the ~~first (SIC)~~ contact 1 is dipped in the removing solution 40 of gold so that the gold plating layer at the portion is removed, as shown in FIGS. 15A and 15B. A bathtub 15 having an opening at topside is provided at an end of a jig 14, and the removing solution 40 of gold is filled in the bathtub 15. Furthermore, positioning protrusions 16 are provided on an upper face of the jig 14. Still furthermore, a pressing plate 17 having positioning recesses 18 provided corresponding to the positioning protrusions 16 are disposed above the jig 14. Still furthermore, a cavity 21 having an opening at topside is formed adjacent to the bathtub 15.

Please amend the paragraph on page 22 beginning at line 7 and ending at line 15, as follows:

At that time, even when the removing solution 40 comes up along an inner wall of the bathtub 15 due to surface tension, the removing solution never reaches top the terminal portion 2 according to the opening of the cavity 21 adjoining the ~~jig 14 (SIC)~~ bathtub 15. Consequently, it is possible to prevent the removing of the gold plating layer of the terminal portion 2. On the other hand,

since the contacting portion 3 is not contacted with the jig 14, as shown in FIG. 15B, the gold plating layer of the contacting portion 3 is never removed.

Please amend the paragraph on page 25 beginning at line 13 and ending at line 24, as follows:

The kind of the nickel plating solution is not limited. For example, when nickel sulfamic acid plating solution is used, it is possible to increase electric current density, so that the productivity can be increased. The nickel plating layer 7 is formed so that the thickness of the layer becomes in a range from 0.3 to 10 μm. Furthermore, the kind of the gold-nickel alloy plating solution is not limited. For example, it is preferable to use one having the eutectoid ratio of gold: nickel is in a range from 70:30 to ~~99.9~0.1 (SIC)~~ 99.9:0.1. As an example of the gold-nickel alloy plating solution, the products of NIKKO metal plating Co. Ltd., can be used. The gold-nickel alloy plating layer 80 is formed in a manner so that the thickness of the layer becomes in a range from 0.01 to 0.5 μm.

Please amend the paragraph on page 28 beginning at line 12 and ending at line 20, as follows:

Subsequently, a fifth embodiment of the present invention is described. In the above-mentioned fourth embodiment, the nickel plating layer 7 as the foundation plating is formed on substantially entire surface of the contact 1, and the gold-nickel (Au-Ni) alloy plating layer ~~8 (SIC)~~ 80 is further formed on the

nickel plating layer 7. In the fifth embodiment, a palladium-nickel (Pd-Ni) alloy plating layer 70 is further formed on the nickel plating layer 7 as the foundation plating, and the gold-nickel (Au-Ni) alloy plating layer 80 is formed on the palladium-nickel alloy plating layer 70.

Please amend the paragraph beginning on page 29 at line 9 and ending at line 25, as follows:

The kind of the nickel plating solution is not limited. For example, when nickel sulfamic acid plating solution is used, it is possible to increase electric current density, so that the productivity can be increased. The nickel plating layer 7 is formed so that the thickness of the layer becomes in a range from 0.3 to 10 μm. Furthermore, the kind of the palladium-nickel alloy plating solution is not limited, so that it is preferable to select one by which the electric current density can be increased and the productivity can be increased. The palladium-nickel alloy plating layer 70 is formed so that the thickness of the layer becomes ion a range from 0.01 to 1.0 μm. Still furthermore, the kind of the gold-nickel alloy plating solution is not limited. For example, it is preferable to use one having the eutectoid ratio of gold: nickel is in a range from 70:30 to ~~99.9~0.1 (SIC)~~ 99.9:0.1. As an example of the gold-nickel alloy plating solution, the products of NIKKO metal plating Co. Ltd., can be used. The gold-nickel alloy plating layer 80 is formed in a manner so that the thickness of the layer becomes in a range from 0.01 to 0.5 μm.

Please amend the paragraph on page 30 beginning at line 1 and ending at line 9, as follows:

After forming the nickel plating layer ~~7 (SIC)~~ 7, the palladium-nickel alloy layer 70 and the gold-nickel alloy plating layer 80 are formed on substantially entire surface of the contact 1, the laser beams L are irradiated at a portion where the diffusion preventing area 6 of the melted solder is to be formed, as shown in FIG. 19. The gold-nickel alloy plating layer 80 at the portion irradiated by the laser beams L is melted and evaporated. Consequently, the gold-nickel plating layer 80 is removed, so that the diffusion preventing area 6 where the palladium-nickel alloy plating layer 70 is unsheathed is formed.